

Amendments to the Specification

Please replace the paragraph beginning on page 13, line 3, with the following rewritten paragraph:

D1
--Fig. 12A shows a semiconductor device in accordance with a third embodiment to which this invention is applied;--

Please add the following paragraph between the paragraph beginning on page 13, line 3, and the paragraph beginning on page 13, line 5, with the following rewritten paragraph:

D2
--Fig. 12B shows the semiconductor device of Fig. 12A with the substrate and resin separated;--

Please replace the paragraph beginning on page 25, line 12, with the following rewritten paragraph:

D3
--A semiconductor device in accordance with a third embodiment to which this invention is applied is shown in Figs. 12A and 12B. The semiconductor device of Figs. 12A and 12B comprises a substrate 50 that has formed individual products and resin 52 that seals a plurality of semiconductor chips that were mounted on the substrate 50. A thinner portion 56 is formed in the substrate 50 at each of corner portions 54 of the semiconductor device. The thinner portion 56 is formed as a depression in at least one of the upper and lower surfaces of the substrate 50. The thickness of the thinner portion 56 is preferably between approximately 1/3 and 1/4 of the thickness of the substrate 50, by way of example. The size of the thinner portion 56 (or the diameter thereof, if circular) is preferably greater than the thickness of the cutting tool (when viewed from a direction perpendicular to the substrate 50). If the depression is placed facing into the resin 52, as shown in Fig. 12, the resin 52 could cover that depression. Alternatively, the depression could be on the opposite side from the resin 52. The formation of the thinner portion 56 ensures that the depression of the substrate 50 is indented further inward than the edge surfaces of the resin 52.--

Amendments to the Drawings:

The attached replacement drawing sheet deletes Fig. 12 and replaces the original sheet with Figs. 11A and 11B.

The attached additional sheet includes Figs. 12A and 12B showing a semiconductor device in accordance with a third embodiment of the invention.

Attachments: Replacement Sheet (Figures 11A and 11B)
Additional Sheet (Figures 12A and 12B)